



Schaltkreis- und Systementwurf

Teil 4: Digitale CMOS Schaltungen

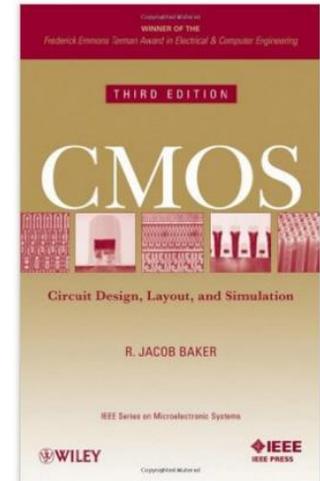


- CMOS Technologie und CMOS Logik
- **Vertiefung:** Timing von CMOS Schaltungen
- **Vertiefung:** Verlustleistung von CMOS Schaltungen
- Standardzellenbibliotheken und SRAM Compiler
- I/O Schaltungen

→ Details siehe Vorlesung
digitale Schaltungstechnik

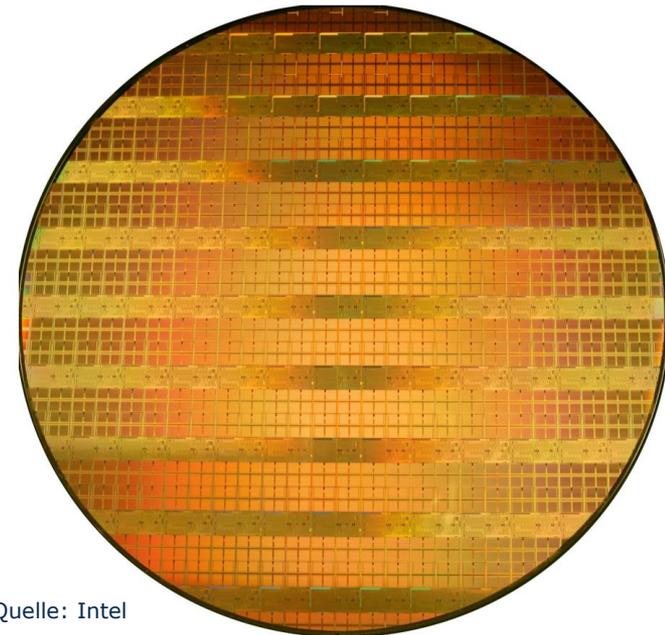
- Ergänzende Vorlesungen:
 - Elektronische Bauelemente
 - Halbleitertechnologie
 - Schaltungstechnik
- Weiterführende Vorlesungen:
 - VLSI Prozessorentwurf
 - Neuromorphe VLSI-Systeme

- Literaturempfehlungen:
 - CMOS, Circuit Design, Layout and Simulation; R. Jacob Baker; IEEE Press Series on Microelectronic Systems, 3rd Edition, 2011
 - Halbleiter-Schaltungstechnik; Ulrich Tietze, Christoph Schenk; Springer; 2002

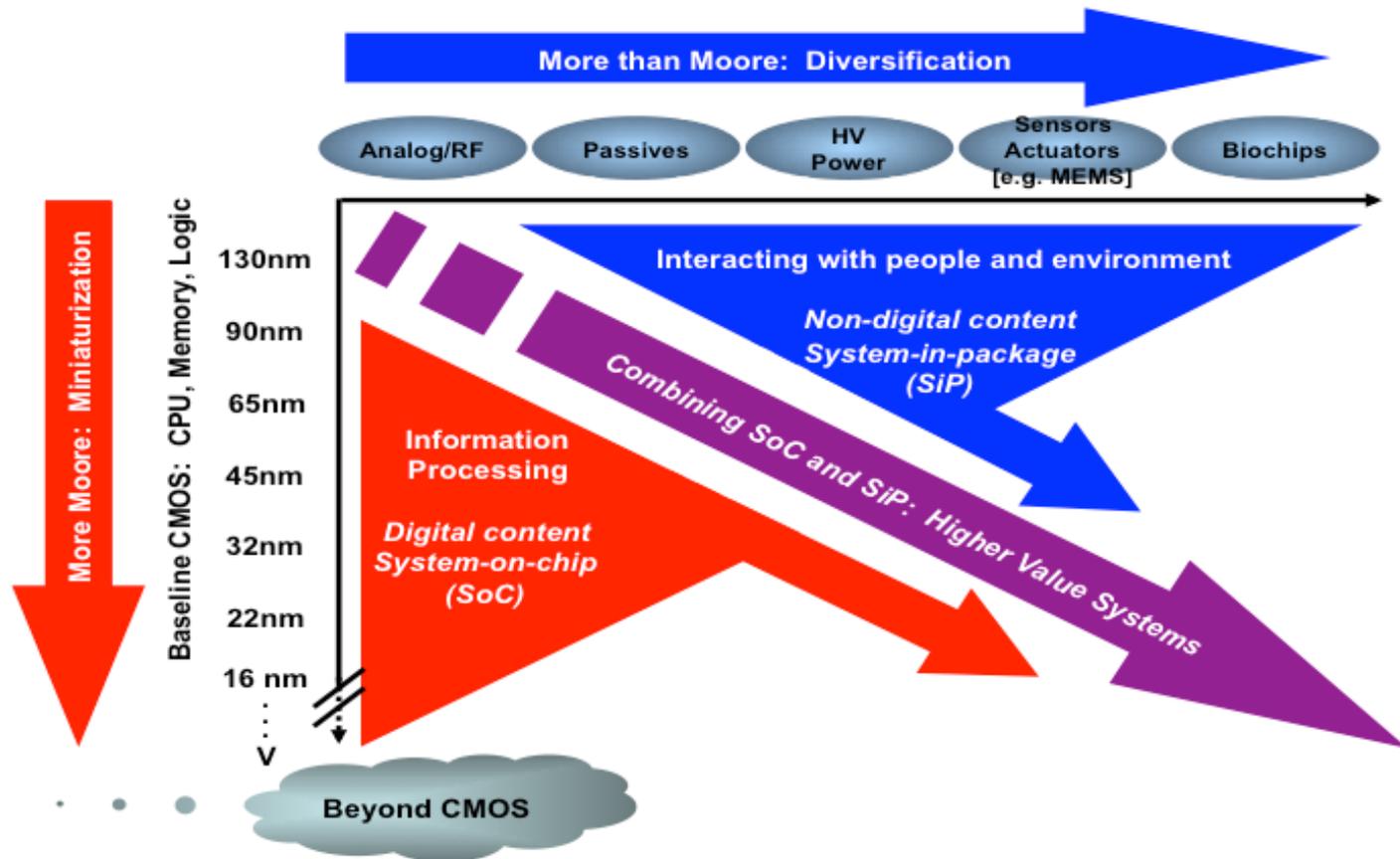


CMOS Technologie

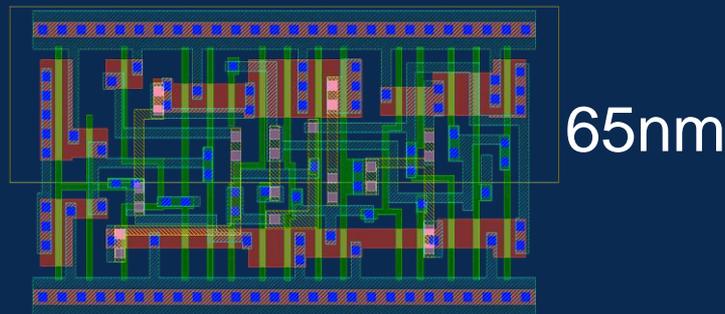
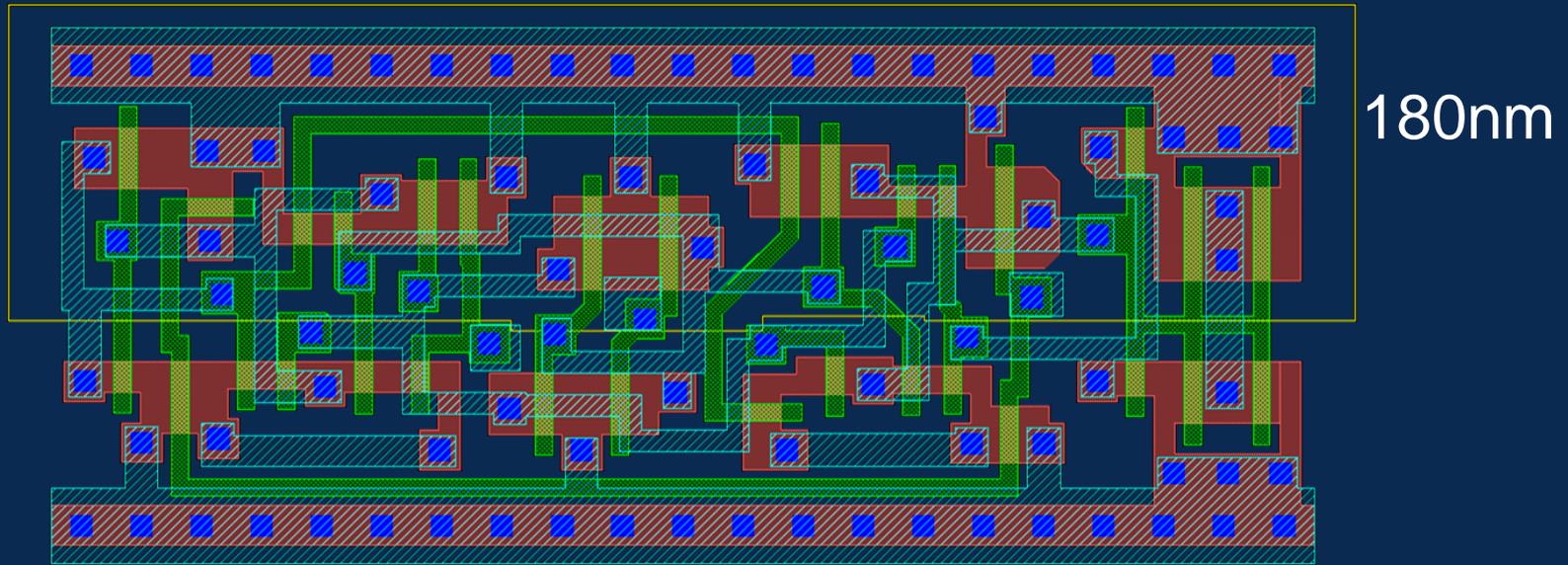
- Complementary Metal Oxide Semiconductor (CMOS) Technologie
- Integration von n-Kanal (NMOS) und p-Kanal (PMOS) Feldeffekttransistoren auf einem Siliziumchip
- Halbleiterprozess zur kostengünstigen Herstellung von integrierten digitalen, analogen und Mixed-Signal Schaltungen
- Herstellung im Waferprozess



Quelle: Intel



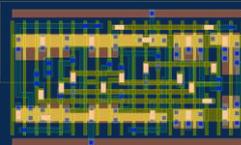
Quelle: International Technology Roadmap for Semiconductors



D-Flip-Flop

Drawn to Scale

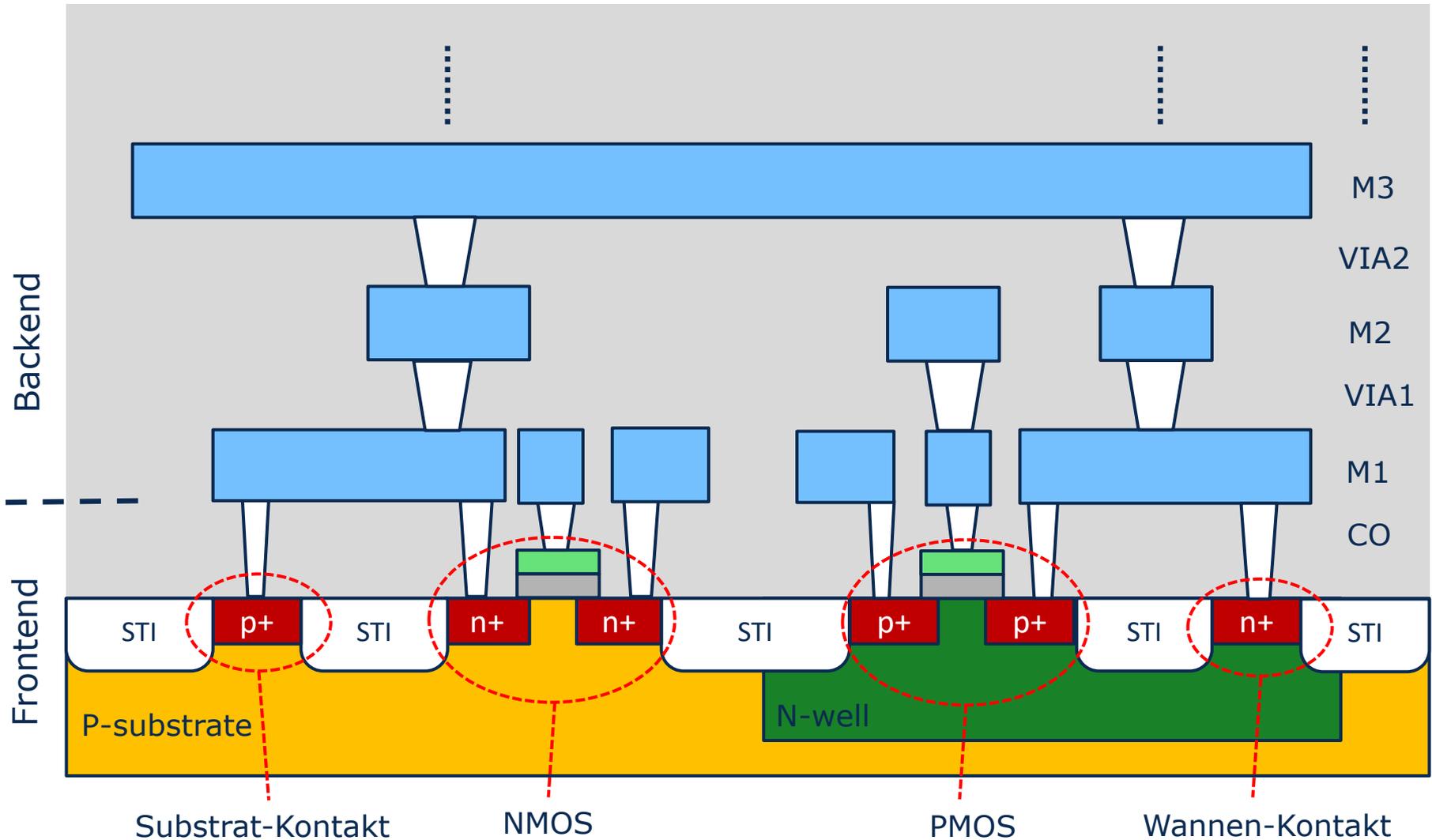
— 1000 nm

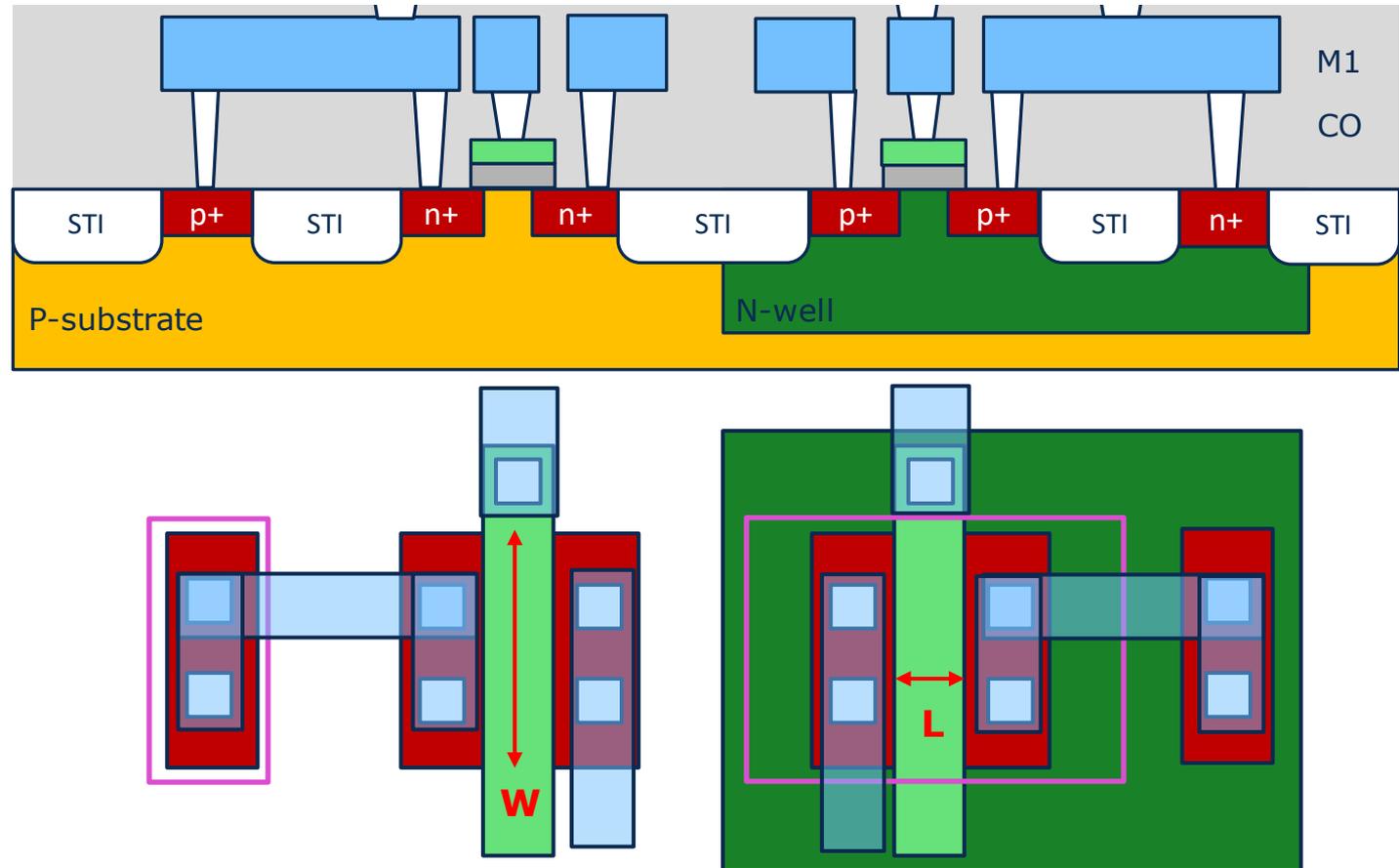
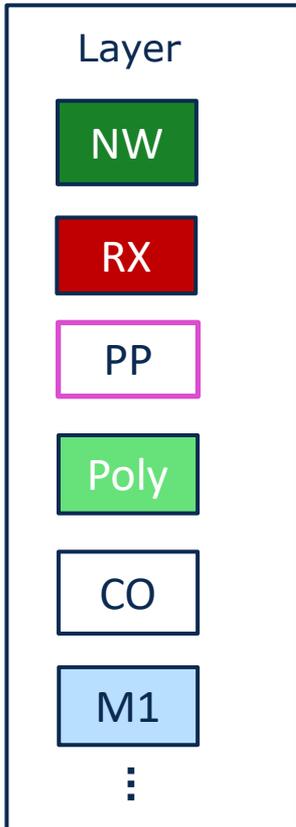


28nm



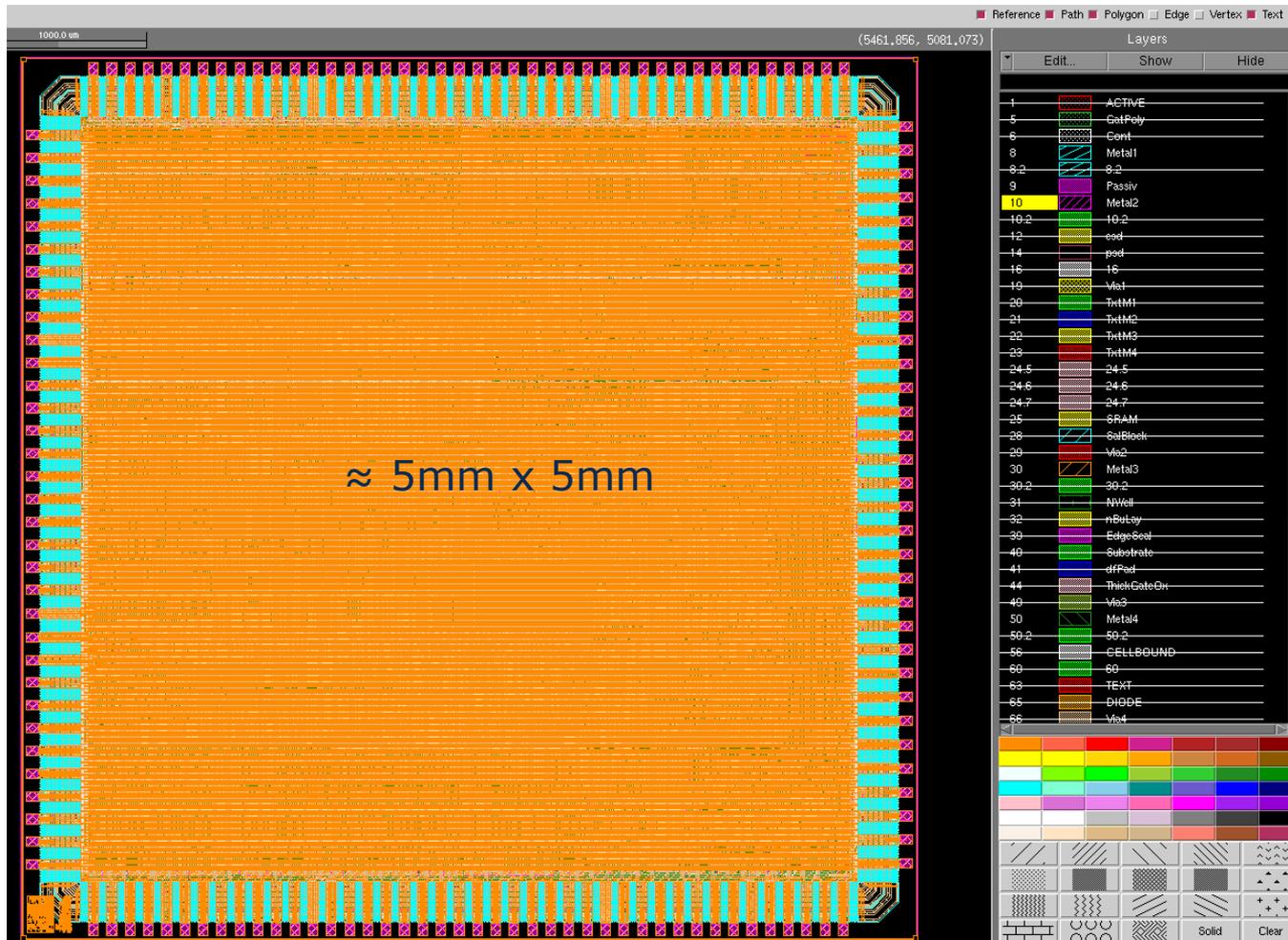
No End of the Road yet

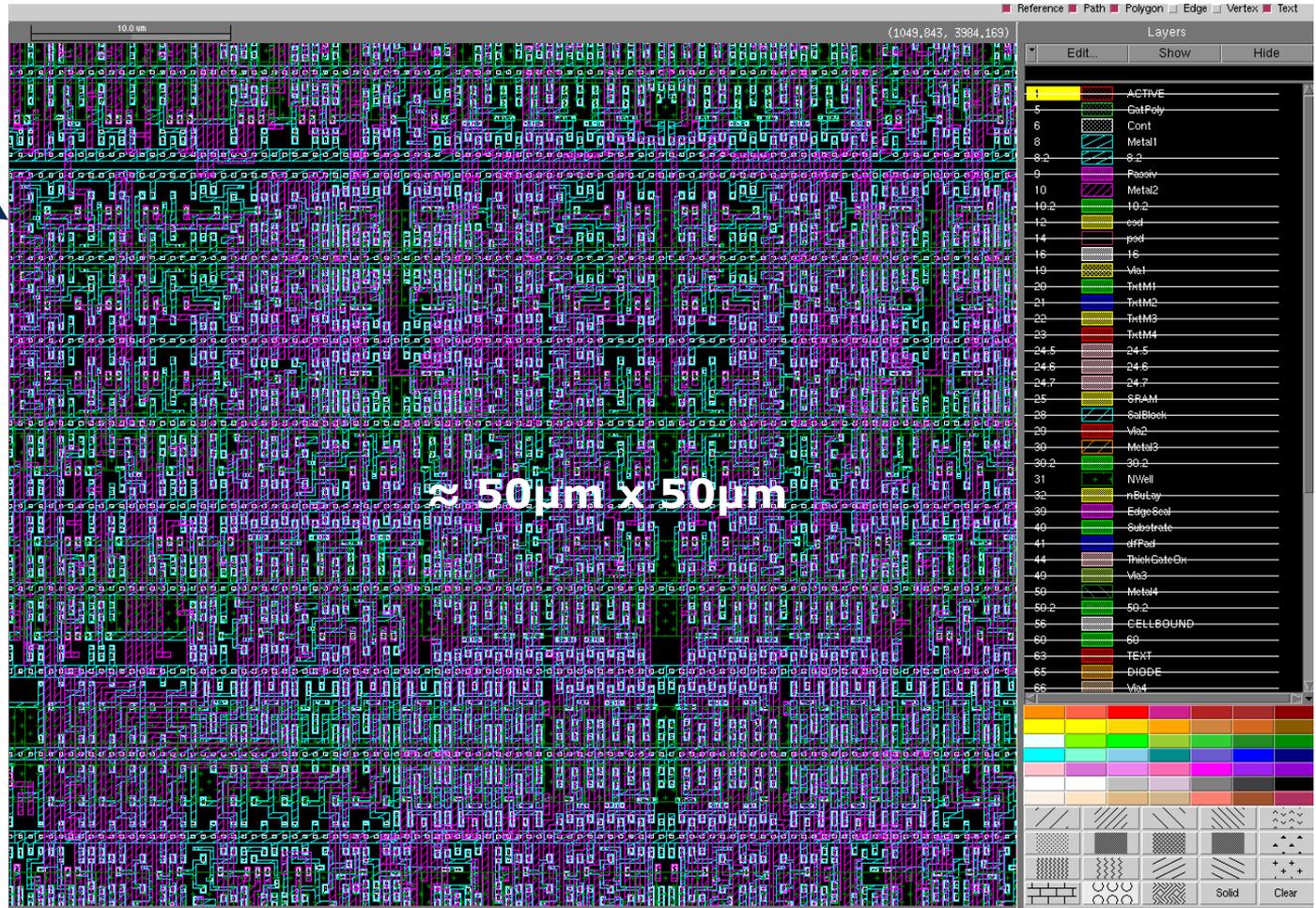
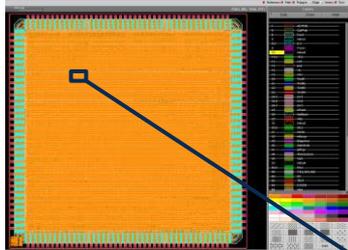


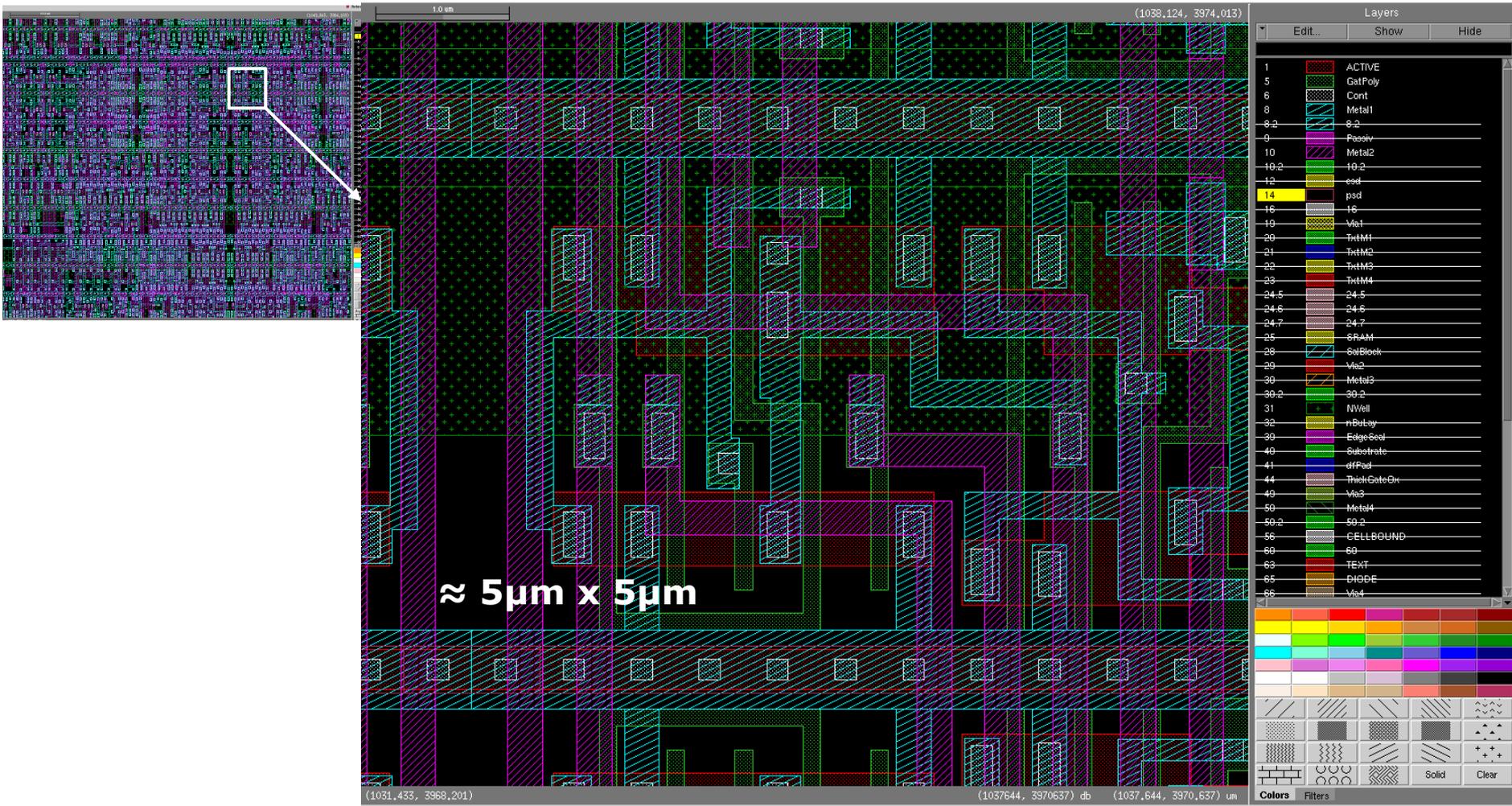


- Freiheitsgrade des Designers beim Schaltungsentwurf/Layoutentwurf:
 - Positionierung und Verdrahtung von NMOS und PMOS Transistoren
 - Transistor Parameter: W , L

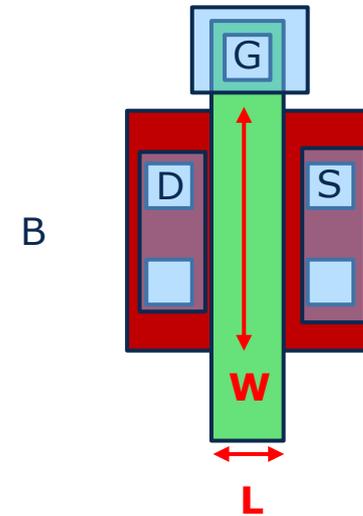
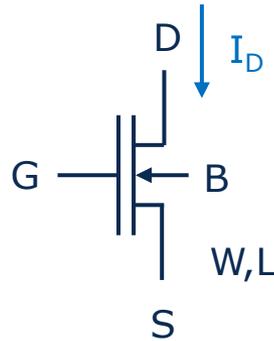
- Layout zur Herstellung der Masken zur Chip Fertigung



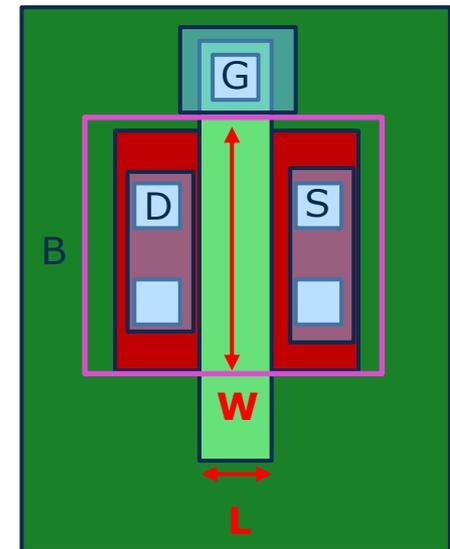
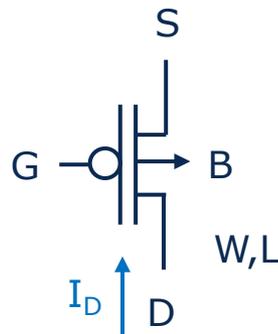




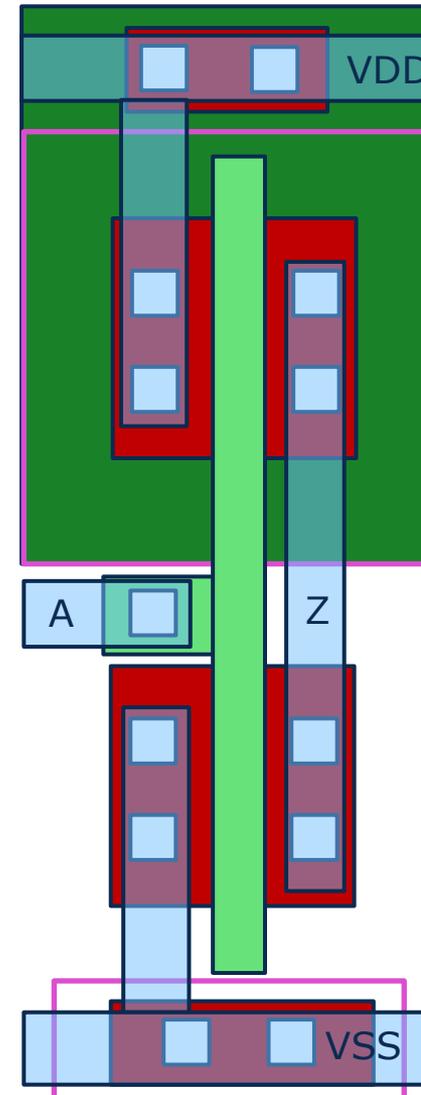
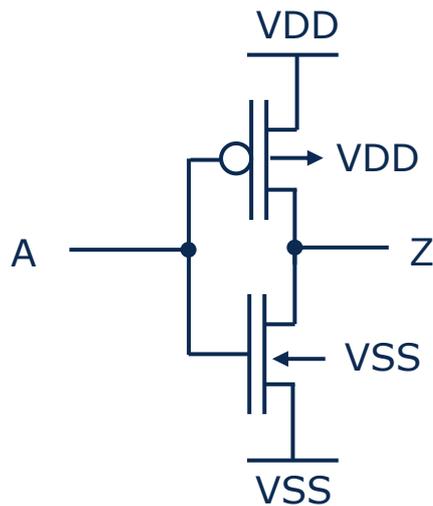
- NMOS Transistor:

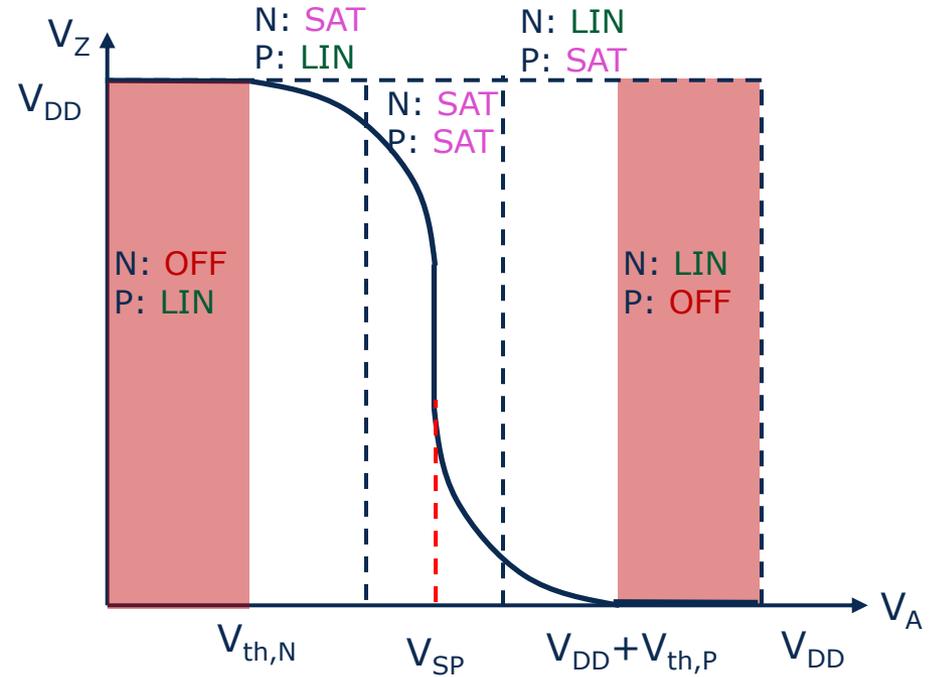
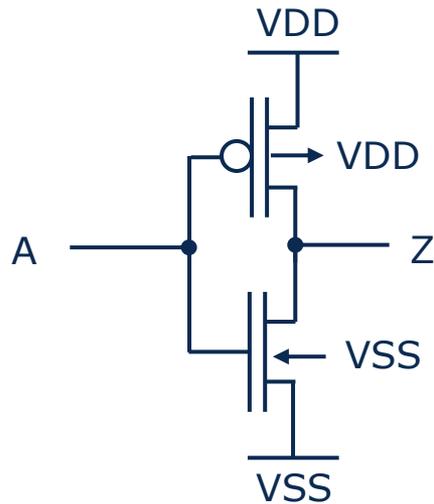


- PMOS Transistor:



- Grundelement der CMOS Logik





- Berechnung der Schaltschwelle (SP):
- N: SAT, PMOS: SAT (Annahme: $\lambda=0$)

- $I_{D,N} = -I_{D,P}$

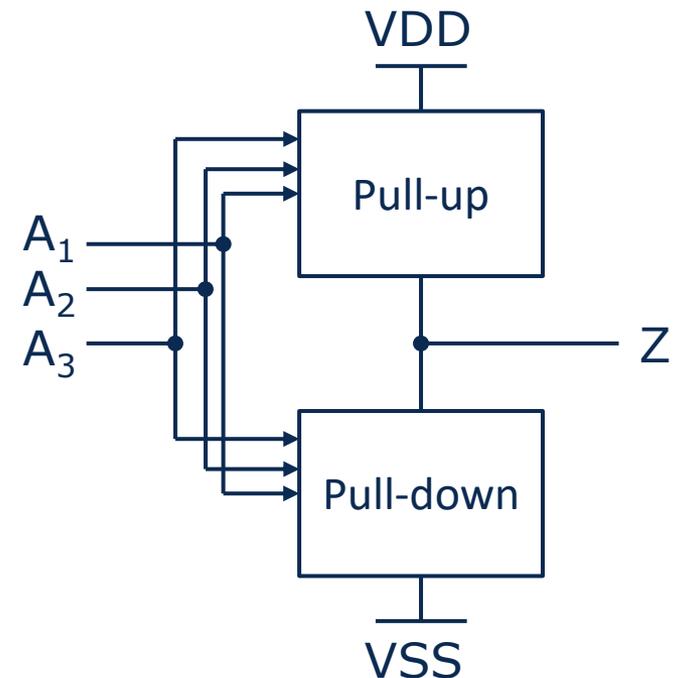
- $\frac{\beta_N}{2} (V_{SP} - V_{th,N})^2 = -\frac{\beta_P}{2} (V_{SP} - V_{DD} - V_{th,P})^2$

- $\rightarrow V_{SP} = \frac{(V_{DD} + V_{th,P}) - \sqrt{\frac{\beta_N}{-\beta_P}} \cdot V_{th,N}}{1 - \sqrt{\frac{\beta_N}{-\beta_P}}}$

- $\rightarrow \frac{-\beta_P}{\beta_N} = \left(\frac{V_{SP} - V_{th,N}}{V_{SP} - V_{DD} - V_{th,P}} \right)^2$

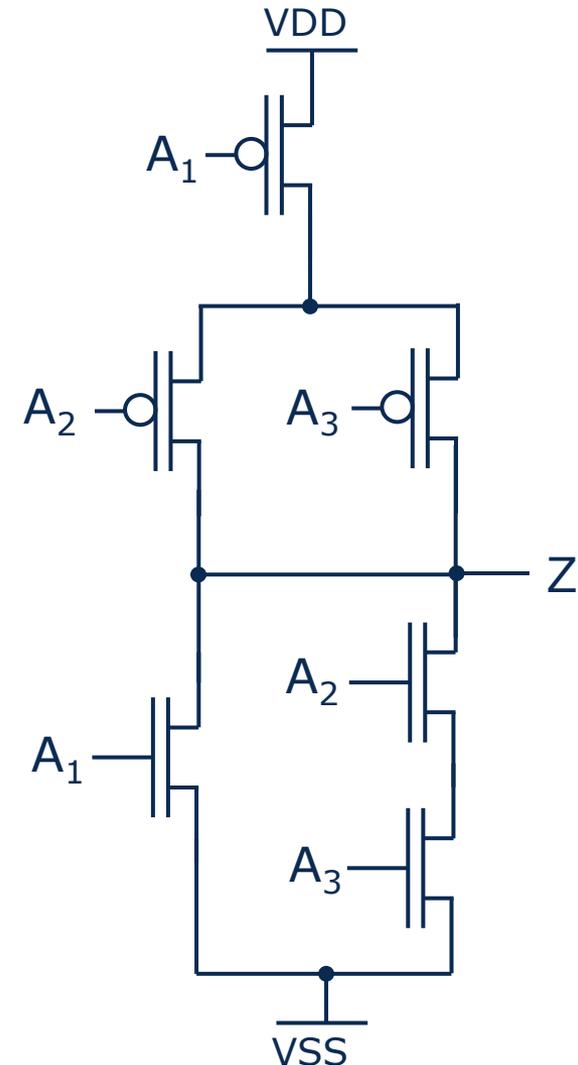
CMOS Logik

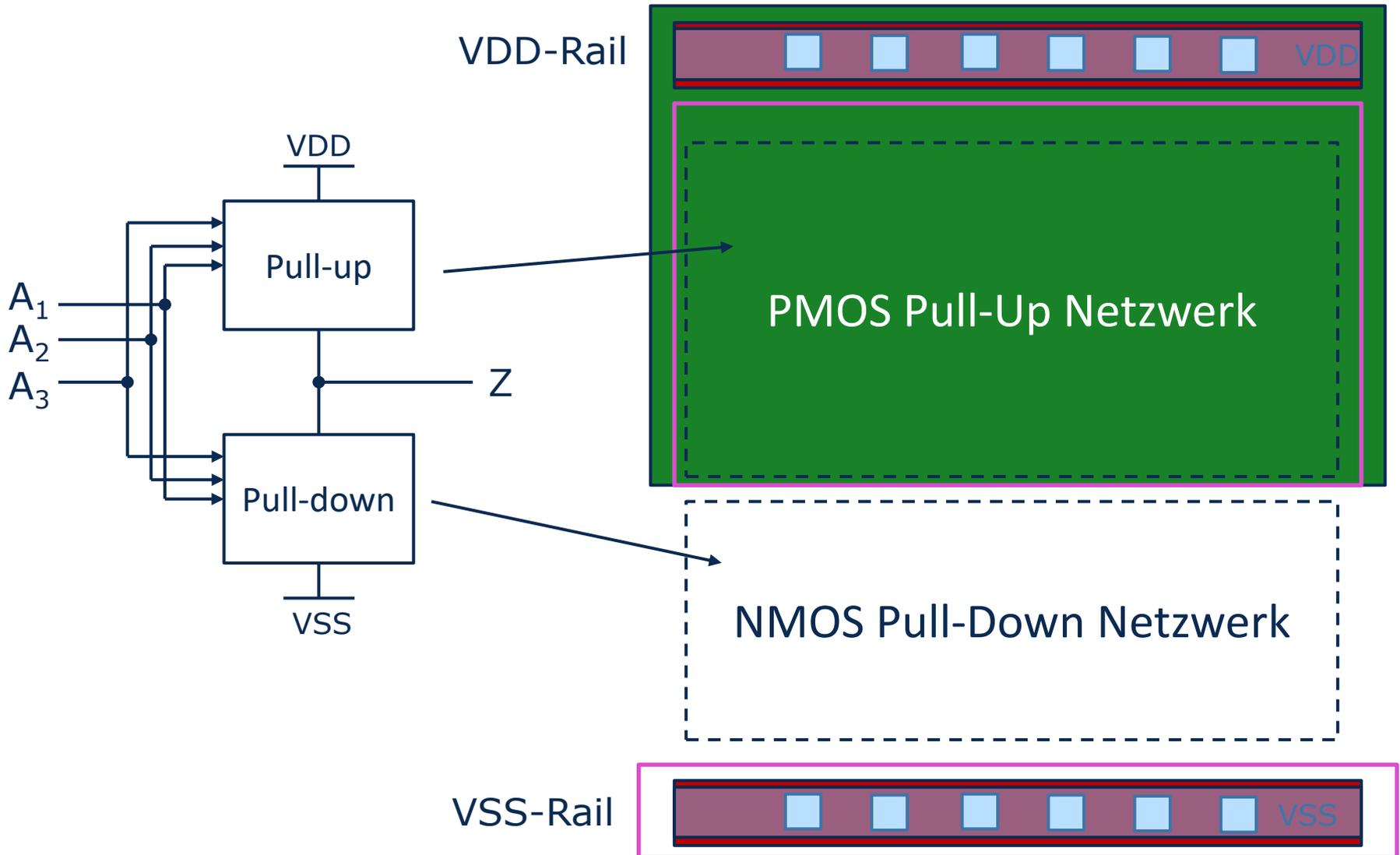
- Pull-Up Netzwerke (PMOS):
 - $Z = F(\overline{A_1}, \overline{A_2}, \overline{A_3}, \dots)$
- Pull-Down Netzwerke (NMOS):
 - $\overline{Z} = G(A_1, A_2, A_3, \dots)$
- **UND** Verknüpfung durch
Reihenschaltung von Transistoren
- **ODER** Verknüpfung durch
Parallelschaltung von Transistoren

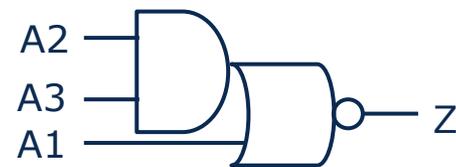
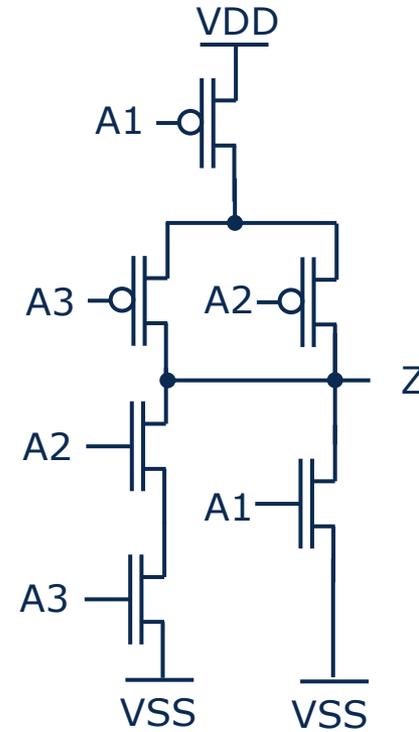
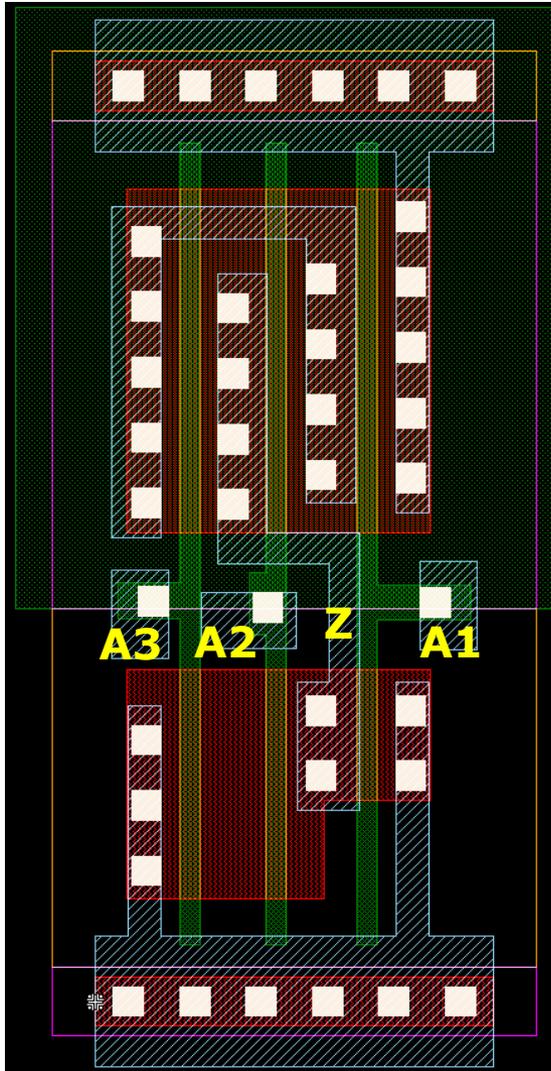


- Logikfunktion: $\bar{Z} = A_1 + A_2A_3$
- Pull-Up Netzwerk:
 - $Z = \overline{A_1 + A_2A_3} = \overline{A_1} \cdot (\overline{A_2} + \overline{A_3})$
- Pull-Down Netzwerk:
 - $\bar{Z} = A_1 + A_2A_3$

→ AOI12 Gatter







AOI2

- Realisierung von des Schreibvorgangs auf einen **Speicherknoten** durch **Tri-State Treiber**
- Rückkopplung durch statische CMOS Logik → **Keeper**
 - Statischer Speicher → Kompensation von Leckströmen

